M25P64

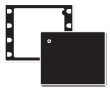
64 Mbit, Low Voltage, Serial Flash Memory With 50MHz SPI Bus Interface

PRELIMINARY DATA

FEATURES SUMMARY

- 64Mbit of Flash Memory
- Page Program (up to 256 Bytes) in 1.4ms (typical)
- Sector Erase (512Kbit)
- Bulk Erase (64Mbit)
- 2.7 to 3.6V Single Supply Voltage
- SPI Bus Compatible Serial Interface
- 50MHz Clock Rate (maximum)
- Electronic Signatures
  - JEDEC Standard Two-Byte Signature (2017h)
  - RES Instruction, One-Byte, Signature (16h), for backward compatibility
- More than 100000 Erase/Program Cycles per Sector
- More than 20-Year Data Retention

Figure 1. Packages



VDFPN8 (ME)
8x6mm (MLP8)



SO16 (MF)
300 mils width

This is preliminary information on a new product now in development or undergoing evaluation. Details are subject to change without notice.

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SUMMARY DESCRIPTION

The M25P64 is a 64Mbit (8M x 8) Serial Flash Memory, with advanced write protection mechanisms, accessed by a high speed SPI-compatible bus.

The memory can be programmed 1 to 256 bytes at a time, using the Page Program instruction.

The memory is organized as 128 sectors, each containing 256 pages. Each page is 256 bytes wide. Thus, the whole memory can be viewed as consisting of 32768 pages, or 8388608 bytes.

The whole memory can be erased using the Bulk Erase instruction, or a sector at a time, using the Sector Erase instruction.

Figure 2. Logic Diagram

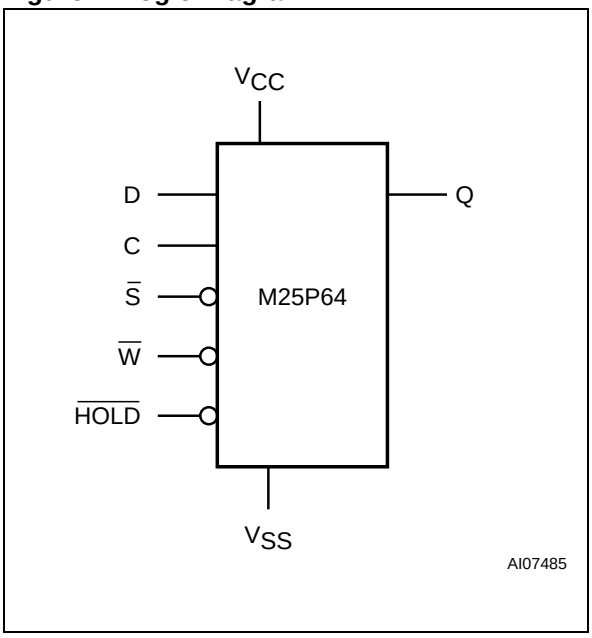
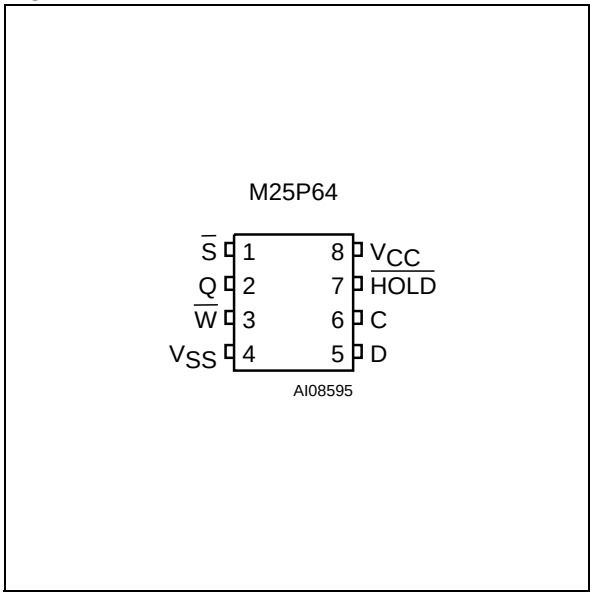


Table 1. Signal Names

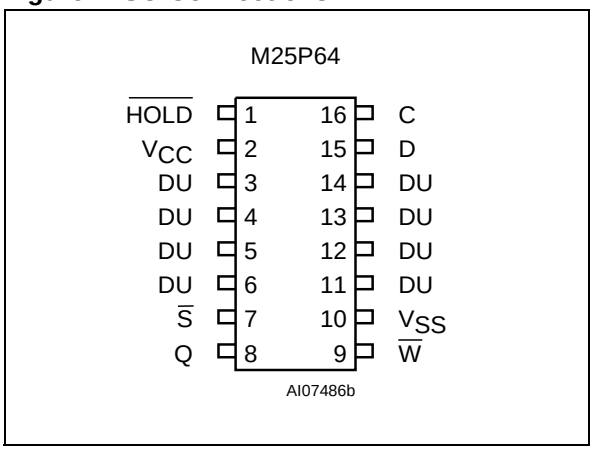
C	Serial Clock
D	Serial Data Input
Q	Serial Data Output
$\overline{S}$	Chip Select
$\overline{W}$	Write Protect
$\overline{HOLD}$	Hold
V_{CC}	Supply Voltage
V_{SS}	Ground

Figure 3. VDFPN Connections



Note: 1. There is an exposed die paddle on the underside of the MLP8 package. This is pulled, internally, to V_{SS}, and must not be allowed to be connected to any other voltage or signal line on the PCB.
2. See PACKAGE MECHANICAL section for package dimensions, and how to identify pin-1.

Figure 4. SO Connections



Note: 1. DU = Don't Use
2. See PACKAGE MECHANICAL section for package dimensions, and how to identify pin-1.

SIGNAL DESCRIPTION

Serial Data Output (Q). This output signal is used to transfer data serially out of the device. Data is shifted out on the falling edge of Serial Clock (C).

Serial Data Input (D). This input signal is used to transfer data serially into the device. It receives instructions, addresses, and the data to be programmed. Values are latched on the rising edge of Serial Clock (C).

Serial Clock (C). This input signal provides the timing of the serial interface. Instructions, addresses, or data present at Serial Data Input (D) are latched on the rising edge of Serial Clock (C). Data on Serial Data Output (Q) changes after the falling edge of Serial Clock (C).

Chip Select ($\overline{S}$). When this input signal is High, the device is deselected and Serial Data Output (Q) is at high impedance. Unless an internal Program, Erase or Write Status Register cycle is in progress, the device will be in the Standby Power mode. Driving Chip Select ($\overline{S}$) Low selects the device, placing it in the Active Power mode.

After Power-up, a falling edge on Chip Select ($\overline{S}$) is required prior to the start of any instruction.

Hold ($\overline{HOLD}$). The Hold ($\overline{HOLD}$) signal is used to pause any serial communications with the device without deselecting the device.

During the Hold condition, the Serial Data Output (Q) is high impedance, and Serial Data Input (D) and Serial Clock (C) are Don't Care.

To start the Hold condition, the device must be selected, with Chip Select ($\overline{S}$) driven Low.

Write Protect ($\overline{W}$). The main purpose of this input signal is to freeze the size of the area of memory that is protected against program or erase instructions (as specified by the values in the BP2, BP1 and BP0 bits of the Status Register).

SPI MODES

These devices can be driven by a microcontroller with its SPI peripheral running in either of the two following modes:

– CPOL=0, CPHA=0

– CPOL=1, CPHA=1

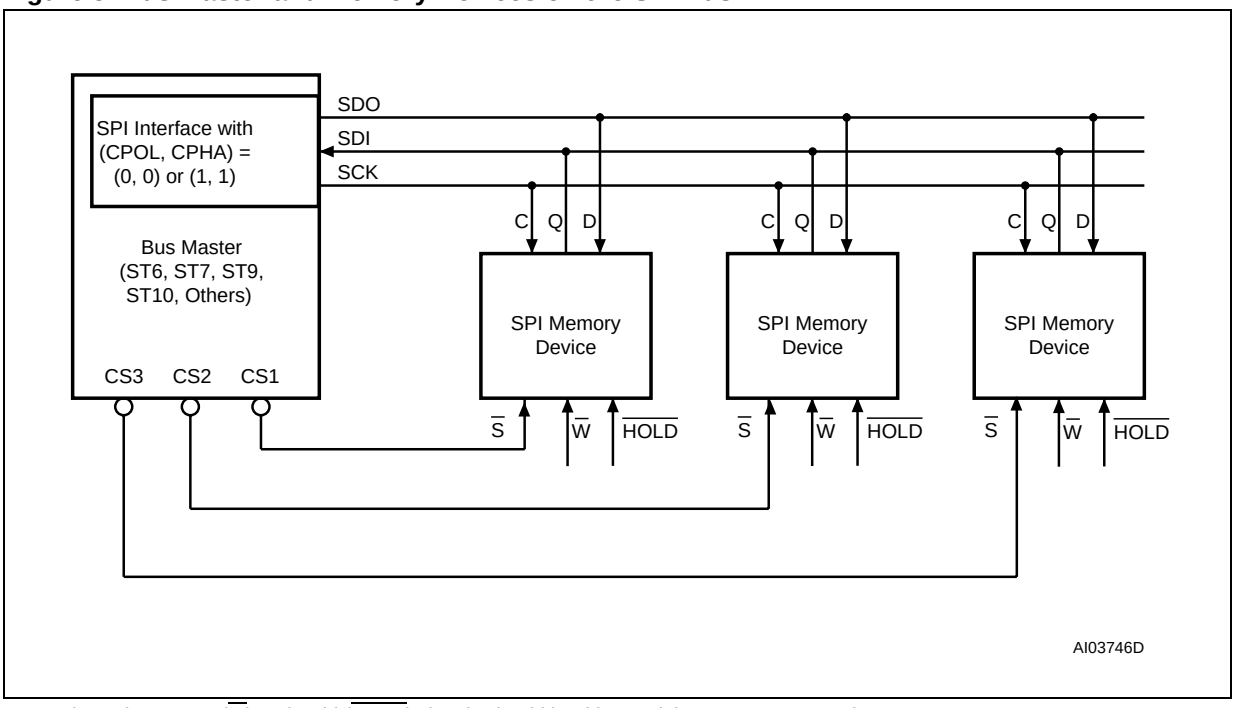
For these two modes, input data is latched in on the rising edge of Serial Clock (C), and output data is available from the falling edge of Serial Clock (C).

The difference between the two modes, as shown in Figure 6., is the clock polarity when the bus master is in Stand-by mode and not transferring data:

– C remains at 0 for (CPOL=0, CPHA=0)

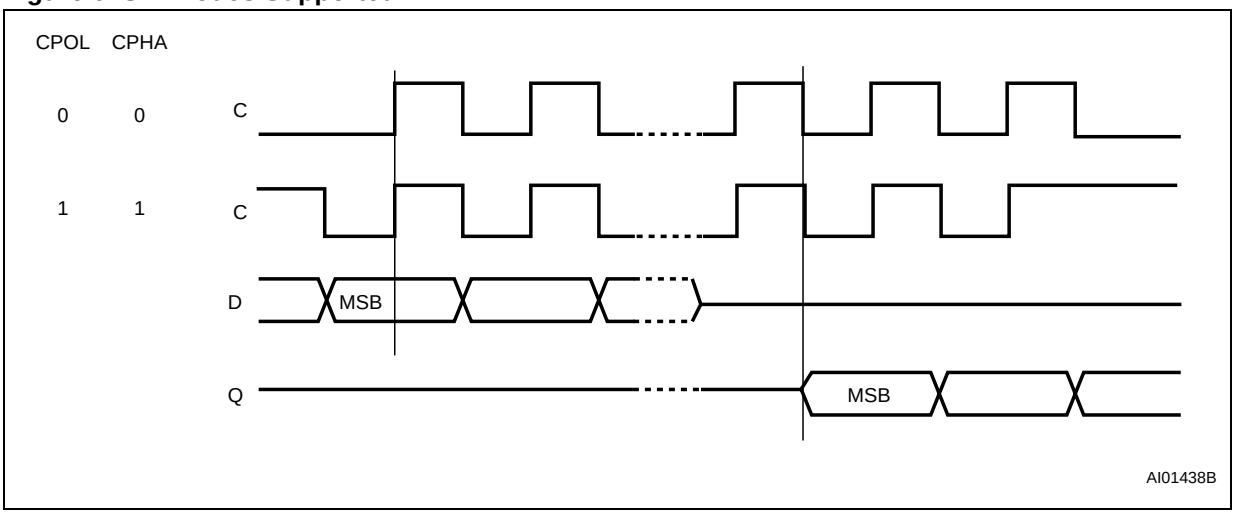
– C remains at 1 for (CPOL=1, CPHA=1)

Figure 5. Bus Master and Memory Devices on the SPI Bus



Note: The Write Protect ($\overline{W}$) and Hold ($\overline{HOLD}$) signals should be driven, High or Low as appropriate.

Figure 6. SPI Modes Supported



OPERATING FEATURES

Page Programming

To program one data byte, two instructions are required: Write Enable (WREN), which is one byte, and a Page Program (PP) sequence, which consists of four bytes plus data. This is followed by the internal Program cycle (of duration t_{PP}).

To spread this overhead, the Page Program (PP) instruction allows up to 256 bytes to be programmed at a time (changing bits from 1 to 0), provided that they lie in consecutive addresses on the same page of memory.

Sector Erase and Bulk Erase

The Page Program (PP) instruction allows bits to be reset from 1 to 0. Before this can be applied, the bytes of memory need to have been erased to all 1s (FFh). This can be achieved either a sector at a time, using the Sector Erase (SE) instruction, or throughout the entire memory, using the Bulk Erase (BE) instruction. This starts an internal Erase cycle (of duration t_{SE} or t_{BE}).

The Erase instruction must be preceded by a Write Enable (WREN) instruction.

Polling During a Write, Program or Erase Cycle

A further improvement in the time to Write Status Register (WRSR), Program (PP) or Erase (SE or BE) can be achieved by not waiting for the worst case delay (t_W, t_{PP}, t_{SE}, or t_{BE}). The Write In Progress (WIP) bit is provided in the Status Register so that the application program can monitor its value, polling it to establish when the previous Write cycle, Program cycle or Erase cycle is complete.

Active Power and Standby Power Modes

When Chip Select ($\overline{S}$) is Low, the device is selected, and in the Active Power mode.

When Chip Select ($\overline{S}$) is High, the device is deselected, but could remain in the Active Power mode until all internal cycles have completed (Program, Erase, Write Status Register). The device then goes in to the Standby Power mode. The device consumption drops to I_{CC1}.

Status Register

The Status Register contains a number of status and control bits that can be read or set (as appropriate) by specific instructions.

WIP bit. The Write In Progress (WIP) bit indicates whether the memory is busy with a Write Status Register, Program or Erase cycle.

WEL bit. The Write Enable Latch (WEL) bit indicates the status of the internal Write Enable Latch.

BP2, BP1, BP0 bits. The Block Protect (BP2, BP1, BP0) bits are non-volatile. They define the size of the area to be software protected against Program and Erase instructions.

SRWD bit. The Status Register Write Disable (SRWD) bit is operated in conjunction with the Write Protect ($\overline{W}$) signal. The Status Register Write Disable (SRWD) bit and Write Protect ($\overline{W}$) signal allow the device to be put in the Hardware Protected mode. In this mode, the non-volatile bits of the Status Register (SRWD, BP2, BP1, BP0) become read-only bits.

Protection Modes

The environments where non-volatile memory devices are used can be very noisy. No SPI device can operate correctly in the presence of excessive noise. To help combat this, the M25P64 features the following data protection mechanisms:

- Power On Reset and an internal timer (t_{PUW}) can provide protection against inadvertant changes while the power supply is outside the operating specification.
- Program, Erase and Write Status Register instructions are checked that they consist of a number of clock pulses that is a multiple of eight, before they are accepted for execution.
- All instructions that modify data must be preceded by a Write Enable (WREN) instruction to set the Write Enable Latch (WEL) bit. This bit is returned to its reset state by the following events:
  - Power-up
  - Write Disable (WRDI) instruction completion
  - Write Status Register (WRSR) instruction completion
  - Page Program (PP) instruction completion
  - Sector Erase (SE) instruction completion
  - Bulk Erase (BE) instruction completion
- The Block Protect (BP2, BP1, BP0) bits allow part of the memory to be configured as read-only. This is the Software Protected Mode (SPM).
- The Write Protect ($\overline{W}$) signal allows the Block Protect (BP2, BP1, BP0) bits and Status Register Write Disable (SRWD) bit to be protected. This is the Hardware Protected Mode (HPM).

Table 2. Protected Area Sizes

Status Register Content			Memory Content	
BP2 Bit	BP1 Bit	BP0 Bit	Protected Area	Unprotected Area
0	0	0	none	All sectors[1] (128 sectors: 0 to 127)
0	0	1	Upper 64th (2 sectors: 126 and 127)	Lower 63/64ths (126 sectors: 0 to 125)
0	1	0	Upper 32nd (4 sectors: 124 to 127)	Lower 31/32nds (124 sectors: 0 to 123)
0	1	1	Upper sixteenth (8 sectors: 120 to 127)	Lower 15/16ths (120 sectors: 0 to 119)
1	0	0	Upper eighth (16 sectors: 112 to 127)	Lower seven-eighths (112 sectors: 0 to 111)
1	0	1	Upper quarter (32 sectors: 96 to 127)	Lower three-quarters (96 sectors: 0 to 95)
1	1	0	Upper half (64 sectors: 64 to 127)	Lower half (64 sectors: 0 to 63)
1	1	1	All sectors (128 sectors: 0 to 127)	none

Note: 1. The device is ready to accept a Bulk Erase instruction if, and only if, all Block Protect (BP2, BP1, BP0) are 0.

Hold Condition

The Hold (HOLD) signal is used to pause any serial communications with the device without resetting the clocking sequence. However, taking this signal Low does not terminate any Write Status Register, Program or Erase cycle that is currently in progress.

To enter the Hold condition, the device must be selected, with Chip Select (S) Low.

The Hold condition starts on the falling edge of the Hold (HOLD) signal, provided that this coincides with Serial Clock (C) being Low (as shown in Figure 7.).

The Hold condition ends on the rising edge of the Hold (HOLD) signal, provided that this coincides with Serial Clock (C) being Low.

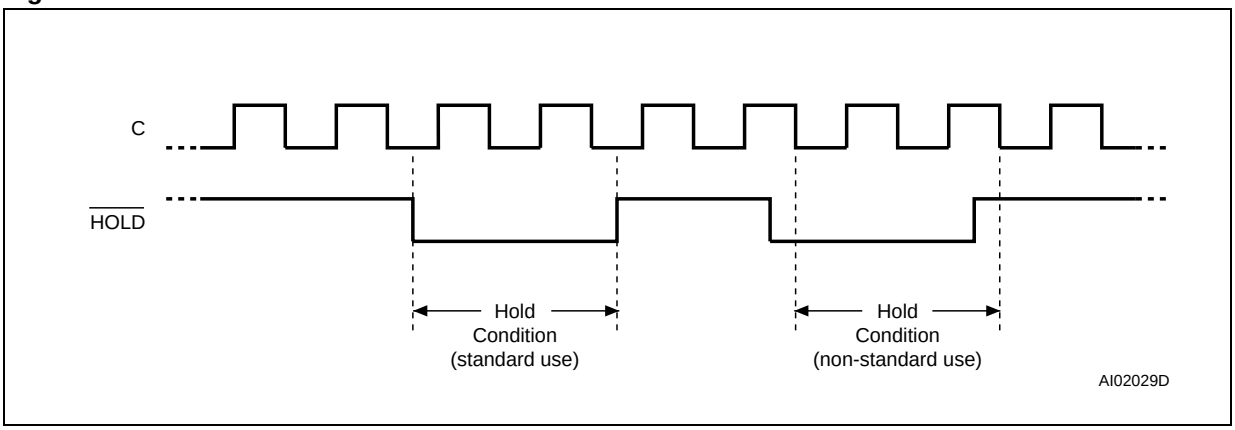
If the falling edge does not coincide with Serial Clock (C) being Low, the Hold condition starts after Serial Clock (C) next goes Low. Similarly, if the rising edge does not coincide with Serial Clock (C) being Low, the Hold condition ends after Serial Clock (C) next goes Low. (This is shown in Figure 7.).

During the Hold condition, the Serial Data Output (Q) is high impedance, and Serial Data Input (D) and Serial Clock (C) are Don't Care.

Normally, the device is kept selected, with Chip Select (S) driven Low, for the whole duration of the Hold condition. This is to ensure that the state of the internal logic remains unchanged from the moment of entering the Hold condition.

If Chip Select (S) goes High while the device is in the Hold condition, this has the effect of resetting the internal logic of the device. To restart communication with the device, it is necessary to drive Hold (HOLD) High, and then to drive Chip Select (S) Low. This prevents the device from going back to the Hold condition.

Figure 7. Hold Condition Activation



MEMORY ORGANIZATION

The memory is organized as:

- 8388608 bytes (8 bits each)
- 128 sectors (512Kbits, 65536 bytes each)
- 32768 pages (256 bytes each).

Each page can be individually programmed (bits are programmed from 1 to 0). The device is Sector or Bulk Erasable (bits are erased from 0 to 1) but not Page Erasable.

Figure 8. Block Diagram

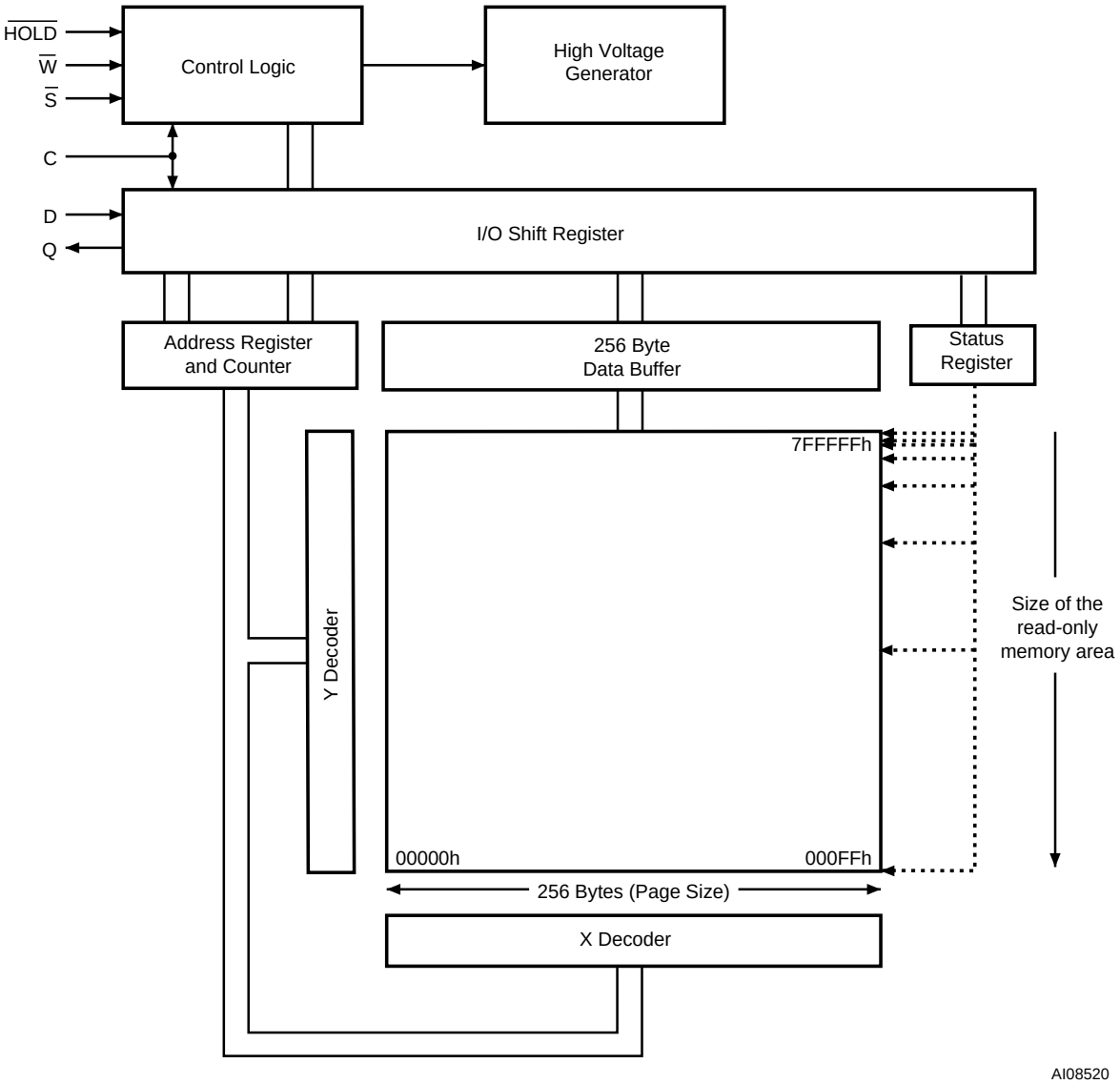


Table 3. Memory Organization

Sector	Address Range	
127	7F0000h	7FFFFFh
126	7E0000h	7EFFFFh
125	7D0000h	7DFFFFh
124	7C0000h	7CFFFFh
123	7B0000h	7BFFFFh
122	7A0000h	7AFFFFh
121	790000h	79FFFFh
120	780000h	78FFFFh
119	770000h	77FFFFh
118	760000h	76FFFFh
117	750000h	75FFFFh
116	740000h	74FFFFh
115	730000h	73FFFFh
114	720000h	72FFFFh
113	710000h	71FFFFh
112	700000h	70FFFFh
111	6F0000h	6FFFFFh
110	6E0000h	6EFFFFh
109	6D0000h	6DFFFFh
108	6C0000h	6CFFFFh
107	6B0000h	6BFFFFh
106	6A0000h	6AFFFFh
105	690000h	69FFFFh
104	680000h	68FFFFh
103	670000h	67FFFFh
102	660000h	66FFFFh
101	650000h	65FFFFh
100	640000h	64FFFFh
99	630000h	63FFFFh
98	620000h	62FFFFh
97	610000h	61FFFFh
96	600000h	60FFFFh
95	5F0000h	5FFFFFh
94	5E0000h	5EFFFFh
93	5D0000h	5DFFFFh
92	5C0000h	5CFFFFh
91	5B0000h	5BFFFFh
90	5A0000h	5AFFFFh
89	590000h	59FFFFh
88	580000h	58FFFFh
87	570000h	57FFFFh
86	560000h	56FFFFh
85	550000h	55FFFFh
84	540000h	54FFFFh
83	530000h	53FFFFh
82	520000h	52FFFFh
81	510000h	51FFFFh
80	500000h	50FFFFh
79	4F0000h	4FFFFFh
78	4E0000h	4EFFFFh
77	4D0000h	4DFFFFh
76	4C0000h	4CFFFFh
75	4B0000h	4BFFFFh
74	4A0000h	4AFFFFh
73	490000h	49FFFFh
72	480000h	48FFFFh
71	470000h	47FFFFh
70	460000h	46FFFFh
69	450000h	45FFFFh
68	440000h	44FFFFh
67	430000h	43FFFFh
66	420000h	42FFFFh
65	410000h	41FFFFh
64	400000h	40FFFFh
63	3F0000h	3FFFFFh
62	3E0000h	3EFFFFh
61	3D0000h	3DFFFFh
60	3C0000h	3CFFFFh
59	3B0000h	3BFFFFh
58	3A0000h	3AFFFFh
57	390000h	39FFFFh

Sector	Address Range	
56	380000h	38FFFFh
55	370000h	37FFFFh
54	360000h	36FFFFh
53	350000h	35FFFFh
52	340000h	34FFFFh
51	330000h	33FFFFh
50	320000h	32FFFFh
49	310000h	31FFFFh
48	300000h	30FFFFh
47	2F0000h	2FFFFFh
46	2E0000h	2EFFFFh
45	2D0000h	2DFFFFh
44	2C0000h	2CFFFFh
43	2B0000h	2BFFFFh
42	2A0000h	2AFFFFh
41	290000h	29FFFFh
40	280000h	28FFFFh
39	270000h	27FFFFh
38	260000h	26FFFFh
37	250000h	25FFFFh
36	240000h	24FFFFh
35	230000h	23FFFFh
34	220000h	22FFFFh
33	210000h	21FFFFh
32	200000h	20FFFFh
31	1F0000h	1FFFFFh
30	1E0000h	1EFFFFh
29	1D0000h	1DFFFFh
28	1C0000h	1CFFFFh
27	1B0000h	1BFFFFh
26	1A0000h	1AFFFFh
25	190000h	19FFFFh
24	180000h	18FFFFh
23	170000h	17FFFFh
22	160000h	16FFFFh
21	150000h	15FFFFh

Sector	Address Range	
20	140000h	14FFFFh
19	130000h	13FFFFh
18	120000h	12FFFFh
17	110000h	11FFFFh
16	100000h	10FFFFh
15	0F0000h	0FFFFFh
14	0E0000h	0EFFFFh
13	0D0000h	0DFFFFh
12	0C0000h	0CFFFFh
11	0B0000h	0BFFFFh
10	0A0000h	0AFFFFh
9	090000h	09FFFFh
8	080000h	08FFFFh
7	070000h	07FFFFh
6	060000h	06FFFFh
5	050000h	05FFFFh
4	040000h	04FFFFh
3	030000h	03FFFFh
2	020000h	02FFFFh
1	010000h	01FFFFh
0	000000h	00FFFFh

INSTRUCTIONS

All instructions, addresses and data are shifted in and out of the device, most significant bit first.

Serial Data Input (D) is sampled on the first rising edge of Serial Clock (C) after Chip Select (S) is driven Low. Then, the one-byte instruction code must be shifted in to the device, most significant bit first, on Serial Data Input (D), each bit being latched on the rising edges of Serial Clock (C).

The instruction set is listed in Table 4..

Every instruction sequence starts with a one-byte instruction code. Depending on the instruction, this might be followed by address bytes, or by data bytes, or by both or none.

In the case of a Read Data Bytes (READ), Read Data Bytes at Higher Speed (Fast_Read), Read Status Register (RDSR), Read Identification (RDID) or Read Electronic Signature (RES) instruction, the shifted-in instruction sequence is followed by a data-out sequence. Chip Select (S) can be driven High after any bit of the data-out sequence is being shifted out.

In the case of a Page Program (PP), Sector Erase (SE), Bulk Erase (BE), Write Status Register (WRSR), Write Enable (WREN) or Write Disable (WRDI), Chip Select (S) must be driven High exactly at a byte boundary, otherwise the instruction is rejected, and is not executed. That is, Chip Select (S) must driven High when the number of clock pulses after Chip Select (S) being driven Low is an exact multiple of eight.

All attempts to access the memory array during a Write Status Register cycle, Program cycle or Erase cycle are ignored, and the internal Write Status Register cycle, Program cycle or Erase cycle continues unaffected.

Table 4. Instruction Set

Instruction	Description	One-byte Instruction Code		Address Bytes	Dummy Bytes	Data Bytes
WREN	Write Enable	0000 0110	06h	0	0	0
WRDI	Write Disable	0000 0100	04h	0	0	0
RDID	Read Identification	1001 1111	9Fh	0	0	1 to 3
RDSR	Read Status Register	0000 0101	05h	0	0	1 to ∞
WRSR	Write Status Register	0000 0001	01h	0	0	1
READ	Read Data Bytes	0000 0011	03h	3	0	1 to ∞
FAST_READ	Read Data Bytes at Higher Speed	0000 1011	0Bh	3	1	1 to ∞
PP	Page Program	0000 0010	02h	3	0	1 to 256
SE	Sector Erase	1101 1000	D8h	3	0	0
BE	Bulk Erase	1100 0111	C7h	0	0	0
RES	Read Electronic Signature	1010 1011	ABh	0	3	1 to ∞

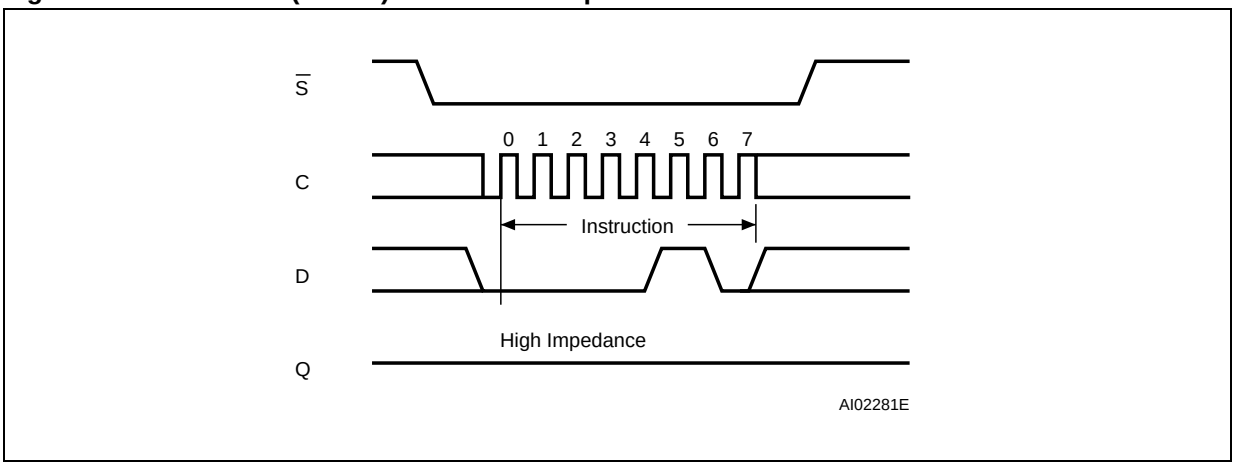
Write Enable (WREN)

The Write Enable (WREN) instruction (Figure 9.) sets the Write Enable Latch (WEL) bit.

The Write Enable Latch (WEL) bit must be set prior to every Page Program (PP), Sector Erase (SE), Bulk Erase (BE) and Write Status Register (WRSR) instruction.

The Write Enable (WREN) instruction is entered by driving Chip Select (S) Low, sending the instruction code, and then driving Chip Select (S) High.

Figure 9. Write Enable (WREN) Instruction Sequence



Write Disable (WRDI)

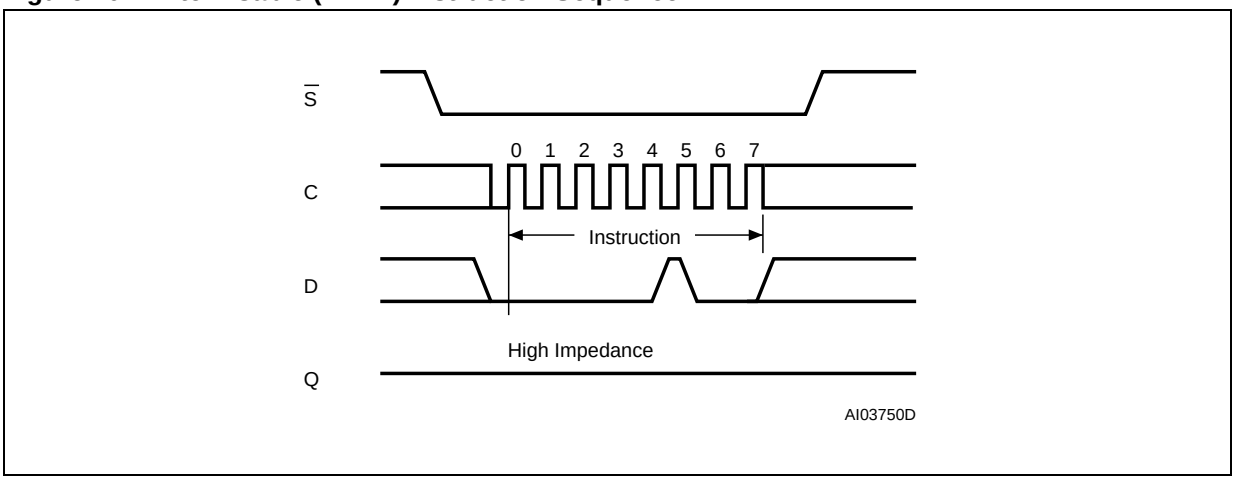
The Write Disable (WRDI) instruction (Figure 10.) resets the Write Enable Latch (WEL) bit.

The Write Disable (WRDI) instruction is entered by driving Chip Select (S) Low, sending the instruction code, and then driving Chip Select (S) High.

The Write Enable Latch (WEL) bit is reset under the following conditions:

- Power-up
- Write Disable (WRDI) instruction completion
- Write Status Register (WRSR) instruction completion
- Page Program (PP) instruction completion
- Sector Erase (SE) instruction completion
- Bulk Erase (BE) instruction completion

Figure 10. Write Disable (WRDI) Instruction Sequence



Read Identification (RDID)

The Read Identification (RDID) instruction allows the 8-bit manufacturer identification to be read, followed by two bytes of device identification. The manufacturer identification is assigned by JEDEC, and has the value 20h for STMicroelectronics. The device identification is assigned by the device manufacturer, and indicates the memory type in the first byte (20h), and the memory capacity of the device in the second byte (17h).

Any Read Identification (RDID) instruction while an Erase or Program cycle is in progress, is not decoded, and has no effect on the cycle that is in progress.

The device is first selected by driving Chip Select (S) Low. Then, the 8-bit instruction code for the instruction is shifted in. This is followed by the 24-bit device identification, stored in the memory, being shifted out on Serial Data Output (Q), each bit being shifted out during the falling edge of Serial Clock (C).

The instruction sequence is shown in Figure 11..

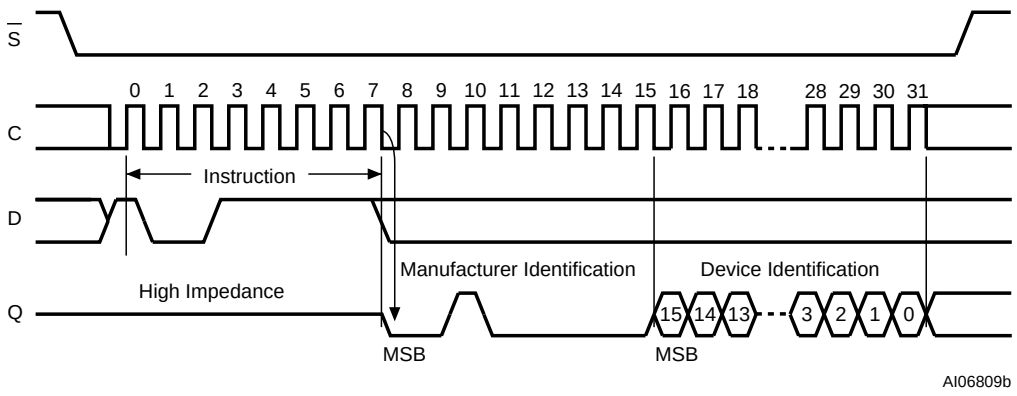
The Read Identification (RDID) instruction is terminated by driving Chip Select (S) High at any time during data output.

When Chip Select (S) is driven High, the device is put in the Standby Power mode. Once in the Standby Power mode, the device waits to be selected, so that it can receive, decode and execute instructions.

Table 5. Read Identification (RDID) Data-Out Sequence

Manufacturer Identification	Device Identification	
	Memory Type	Memory Capacity
20h	20h	17h

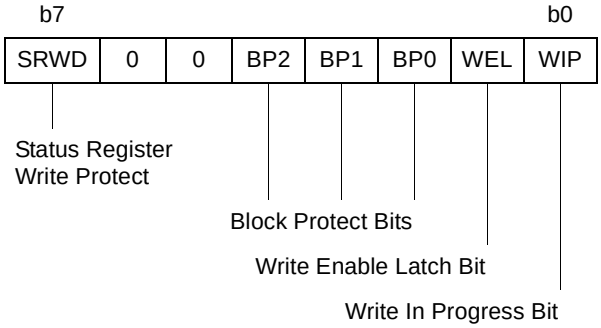
Figure 11. Read Identification (RDID) Instruction Sequence and Data-Out Sequence



Read Status Register (RDSR)

The Read Status Register (RDSR) instruction allows the Status Register to be read. The Status Register may be read at any time, even while a Program, Erase or Write Status Register cycle is in progress. When one of these cycles is in progress, it is recommended to check the Write In Progress (WIP) bit before sending a new instruction to the device. It is also possible to read the Status Register continuously, as shown in Figure 12..

Table 6. Status Register Format



The status and control bits of the Status Register are as follows:

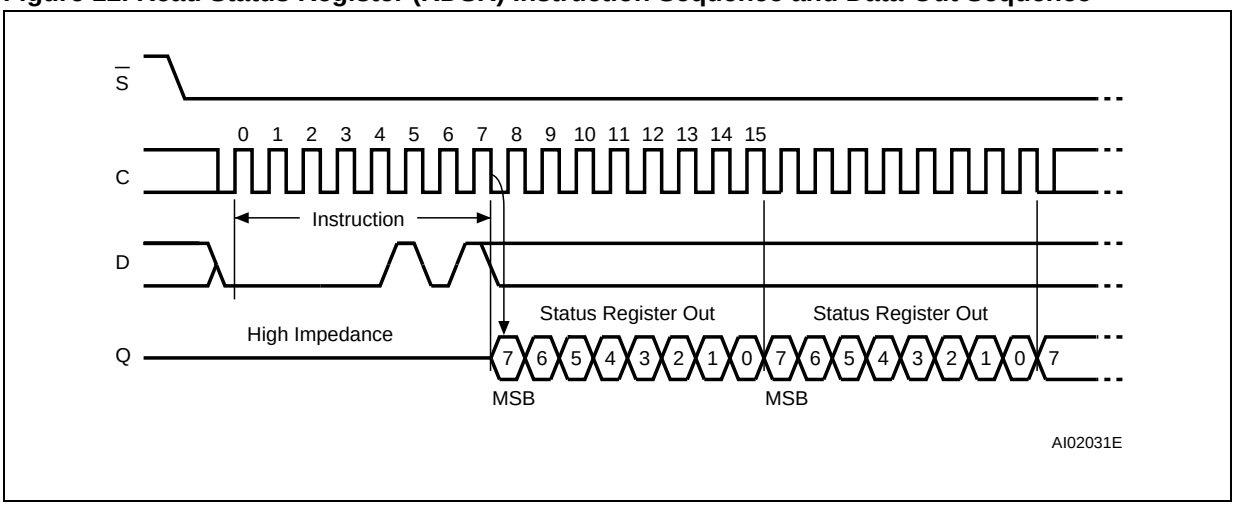
WIP bit. The Write In Progress (WIP) bit indicates whether the memory is busy with a Write Status Register, Program or Erase cycle. When set to 1, such a cycle is in progress, when reset to 0 no such cycle is in progress.

WEL bit. The Write Enable Latch (WEL) bit indicates the status of the internal Write Enable Latch. When set to 1 the internal Write Enable Latch is set, when set to 0 the internal Write Enable Latch is reset and no Write Status Register, Program or Erase instruction is accepted.

BP2, BP1, BP0 bits. The Block Protect (BP2, BP1, BP0) bits are non-volatile. They define the size of the area to be software protected against Program and Erase instructions. These bits are written with the Write Status Register (WRSR) instruction. When one or more of the Block Protect (BP2, BP1, BP0) bits is set to 1, the relevant memory area (as defined in Table 2.) becomes protected against Page Program (PP) and Sector Erase (SE) instructions. The Block Protect (BP2, BP1, BP0) bits can be written provided that the Hardware Protected mode has not been set. The Bulk Erase (BE) instruction is executed if, and only if, all Block Protect (BP2, BP1, BP0) bits are 0.

SRWD bit. The Status Register Write Disable (SRWD) bit is operated in conjunction with the Write Protect (W) signal. The Status Register Write Disable (SRWD) bit and Write Protect (W) signal allow the device to be put in the Hardware Protected mode (when the Status Register Write Disable (SRWD) bit is set to 1, and Write Protect (W) is driven Low). In this mode, the non-volatile bits of the Status Register (SRWD, BP2, BP1, BP0) become read-only bits and the Write Status Register (WRSR) instruction is no longer accepted for execution.

Figure 12. Read Status Register (RDSR) Instruction Sequence and Data-Out Sequence



Write Status Register (WRSR)

The Write Status Register (WRSR) instruction allows new values to be written to the Status Register. Before it can be accepted, a Write Enable (WREN) instruction must previously have been executed. After the Write Enable (WREN) instruction has been decoded and executed, the device sets the Write Enable Latch (WEL).

The Write Status Register (WRSR) instruction is entered by driving Chip Select (S) Low, followed by the instruction code and the data byte on Serial Data Input (D).

The instruction sequence is shown in Figure 13..

The Write Status Register (WRSR) instruction has no effect on b6, b5, b1 and b0 of the Status Register. b6 and b5 are always read as 0.

Chip Select (S) must be driven High after the eighth bit of the data byte has been latched in. If not, the Write Status Register (WRSR) instruction is not executed. As soon as Chip Select (S) is driven High, the self-timed Write Status Register cycle (whose duration is t_W) is initiated. While the Write Status Register cycle is in progress, the Status Register may still be read to check the value of the Write In Progress (WIP) bit. The Write In Progress (WIP) bit is 1 during the self-timed Write Status Register cycle, and is 0 when it is completed. When the cycle is completed, the Write Enable Latch (WEL) is reset.

The Write Status Register (WRSR) instruction allows the user to change the values of the Block Protect (BP2, BP1, BP0) bits, to define the size of the area that is to be treated as read-only, as defined in Table 2.. The Write Status Register (WRSR) instruction also allows the user to set or reset the Status Register Write Disable (SRWD) bit in accordance with the Write Protect (W) signal. The Status Register Write Disable (SRWD) bit and Write Protect (W) signal allow the device to be put in the Hardware Protected Mode (HPM). The Write Status Register (WRSR) instruction is not executed once the Hardware Protected Mode (HPM) is entered.

Table 7. Protection Modes

W Signal	SRWD Bit	Mode	Write Protection of the Status Register	Memory Content	
				Protected Area[1]	Unprotected Area[1]
1	0	Software Protected (SPM)	Status Register is Writable (if the WREN instruction has set the WEL bit) The values in the SRWD, BP2, BP1 and BP0 bits can be changed	Protected against Page Program, Sector Erase and Bulk Erase	Ready to accept Page Program and Sector Erase instructions
0	0				
1	1				
0	1	Hardware Protected (HPM)	Status Register is Hardware write protected The values in the SRWD, BP2, BP1 and BP0 bits cannot be changed	Protected against Page Program, Sector Erase and Bulk Erase	Ready to accept Page Program and Sector Erase instructions

Note: 1. As defined by the values in the Block Protect (BP2, BP1, BP0) bits of the Status Register, as shown in Table 2..

The protection features of the device are summarized in Table 7.

When the Status Register Write Disable (SRWD) bit of the Status Register is 0 (its initial delivery state), it is possible to write to the Status Register provided that the Write Enable Latch (WEL) bit has previously been set by a Write Enable (WREN) instruction, regardless of the whether Write Protect (W) is driven High or Low.

When the Status Register Write Disable (SRWD) bit of the Status Register is set to 1, two cases need to be considered, depending on the state of Write Protect (W):

– If Write Protect (W) is driven High, it is possible to write to the Status Register provided that the Write Enable Latch (WEL) bit has previously been set by a Write Enable (WREN) instruction.

– If Write Protect (W) is driven Low, it is *not* possible to write to the Status Register *even* if the Write Enable Latch (WEL) bit has previously been set by a Write Enable (WREN) instruction. (Attempts to write to the Status Register are rejected, and are not accepted for execution). As a consequence, all the data bytes in the memory area that are software protected (SPM) by the Block Protect (BP2, BP1, BP0) bits of the Status Register, are also hardware protected against data modification.

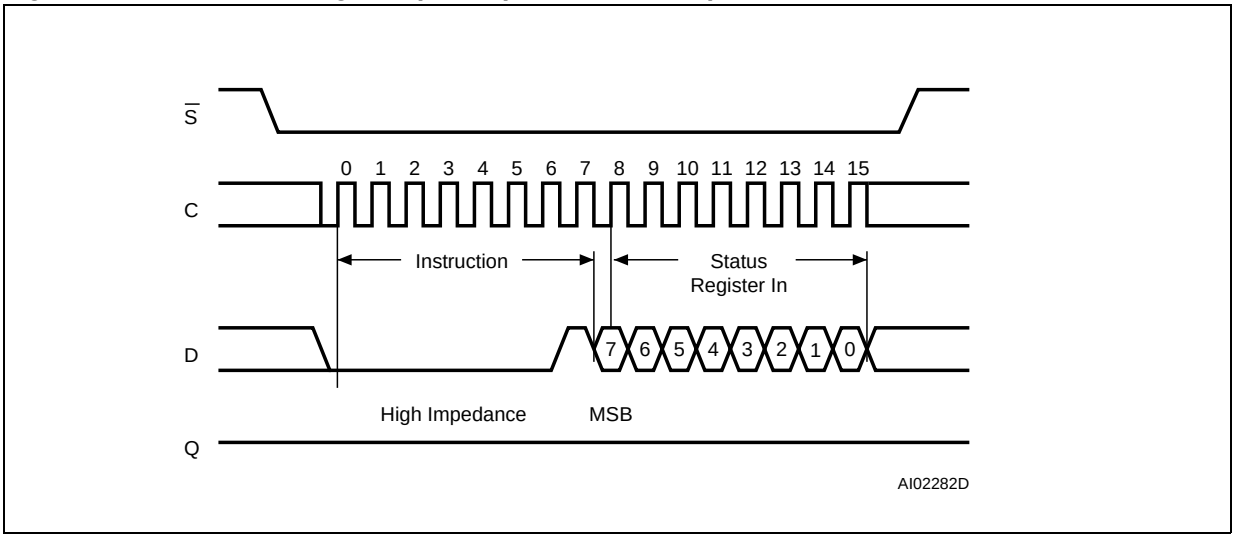
Regardless of the order of the two events, the Hardware Protected Mode (HPM) can be entered:

– by setting the Status Register Write Disable (SRWD) bit after driving Write Protect ($\overline{W}$) Low
– or by driving Write Protect ($\overline{W}$) Low after setting the Status Register Write Disable (SRWD) bit.

The only way to exit the Hardware Protected Mode (HPM) once entered is to pull Write Protect ($\overline{W}$) High.

If Write Protect ($\overline{W}$) is permanently tied High, the Hardware Protected Mode (HPM) can never be activated, and only the Software Protected Mode (SPM), using the Block Protect (BP2, BP1, BP0) bits of the Status Register, can be used.

Figure 13. Write Status Register (WRSR) Instruction Sequence



Read Data Bytes (READ)

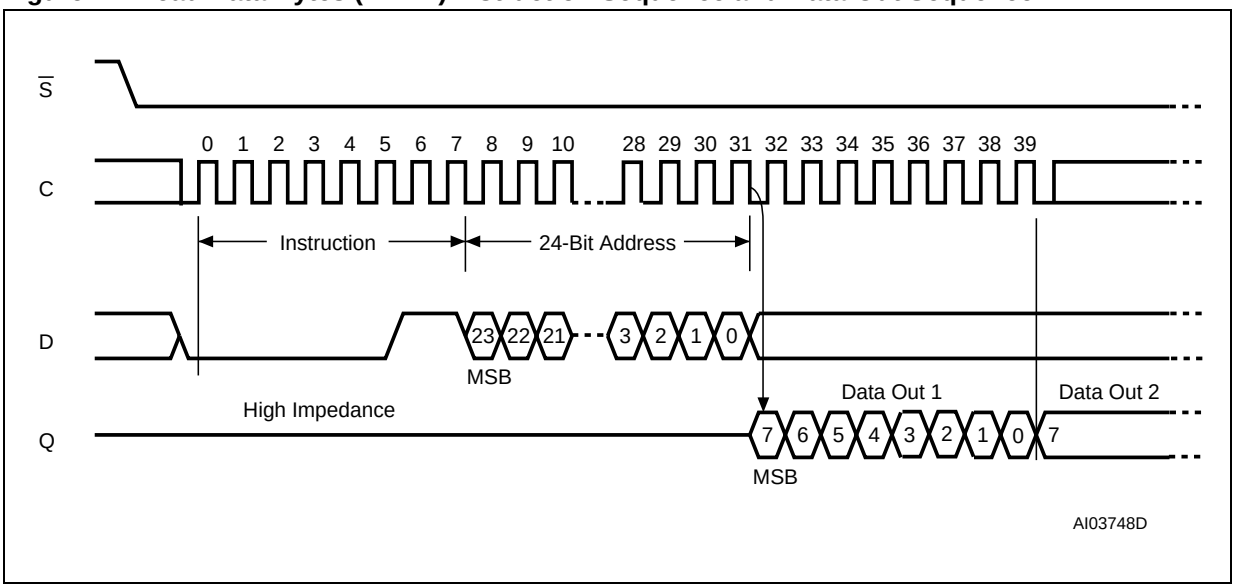
The device is first selected by driving Chip Select (S) Low. The instruction code for the Read Data Bytes (READ) instruction is followed by a 3-byte address (A23-A0), each bit being latched-in during the rising edge of Serial Clock (C). Then the memory contents, at that address, is shifted out on Serial Data Output (Q), each bit being shifted out, at a maximum frequency f_R, during the falling edge of Serial Clock (C).

The instruction sequence is shown in Figure 14..

The first byte addressed can be at any location. The address is automatically incremented to the next higher address after each byte of data is shifted out. The whole memory can, therefore, be read with a single Read Data Bytes (READ) instruction. When the highest address is reached, the address counter rolls over to 000000h, allowing the read sequence to be continued indefinitely.

The Read Data Bytes (READ) instruction is terminated by driving Chip Select (S) High. Chip Select (S) can be driven High at any time during data output. Any Read Data Bytes (READ) instruction, while an Erase, Program or Write cycle is in progress, is rejected without having any effects on the cycle that is in progress.

Figure 14. Read Data Bytes (READ) Instruction Sequence and Data-Out Sequence



Note: 1. Address bit A23 is Don't Care.

Read Data Bytes at Higher Speed (FAST_READ)

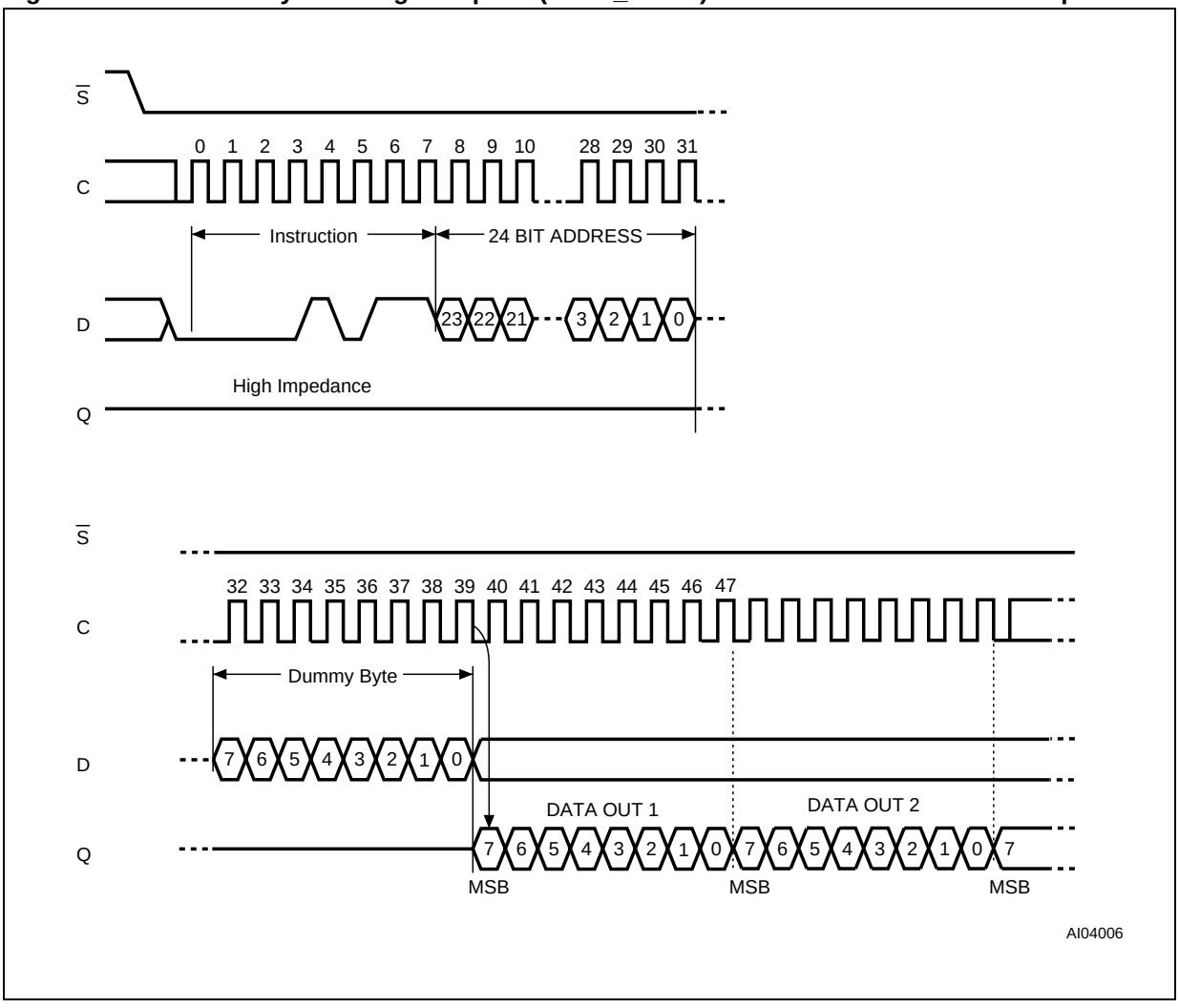
The device is first selected by driving Chip Select (S) Low. The instruction code for the Read Data Bytes at Higher Speed (FAST_READ) instruction is followed by a 3-byte address (A23-A0) and a dummy byte, each bit being latched-in during the rising edge of Serial Clock (C). Then the memory contents, at that address, is shifted out on Serial Data Output (Q), each bit being shifted out, at a maximum frequency f_C, during the falling edge of Serial Clock (C).

The instruction sequence is shown in Figure 15..

The first byte addressed can be at any location. The address is automatically incremented to the next higher address after each byte of data is shifted out. The whole memory can, therefore, be read with a single Read Data Bytes at Higher Speed (FAST_READ) instruction. When the highest address is reached, the address counter rolls over to 000000h, allowing the read sequence to be continued indefinitely.

The Read Data Bytes at Higher Speed (FAST_READ) instruction is terminated by driving Chip Select (S) High. Chip Select (S) can be driven High at any time during data output. Any Read Data Bytes at Higher Speed (FAST_READ) instruction, while an Erase, Program or Write cycle is in progress, is rejected without having any effects on the cycle that is in progress.

Figure 15. Read Data Bytes at Higher Speed (FAST_READ) Instruction and Data-Out Sequence



Note: Address bit A23 is Don't Care.

Page Program (PP)

The Page Program (PP) instruction allows bytes to be programmed in the memory (changing bits from 1 to 0). Before it can be accepted, a Write Enable (WREN) instruction must previously have been executed. After the Write Enable (WREN) instruction has been decoded, the device sets the Write Enable Latch (WEL).

The Page Program (PP) instruction is entered by driving Chip Select (S) Low, followed by the instruction code, three address bytes and at least one data byte on Serial Data Input (D). If the 8 least significant address bits (A7-A0) are not all zero, all transmitted data that goes beyond the end of the current page are programmed from the start address of the same page (from the address whose 8 least significant bits (A7-A0) are all zero). Chip Select (S) must be driven Low for the entire duration of the sequence.

The instruction sequence is shown in Figure 16..

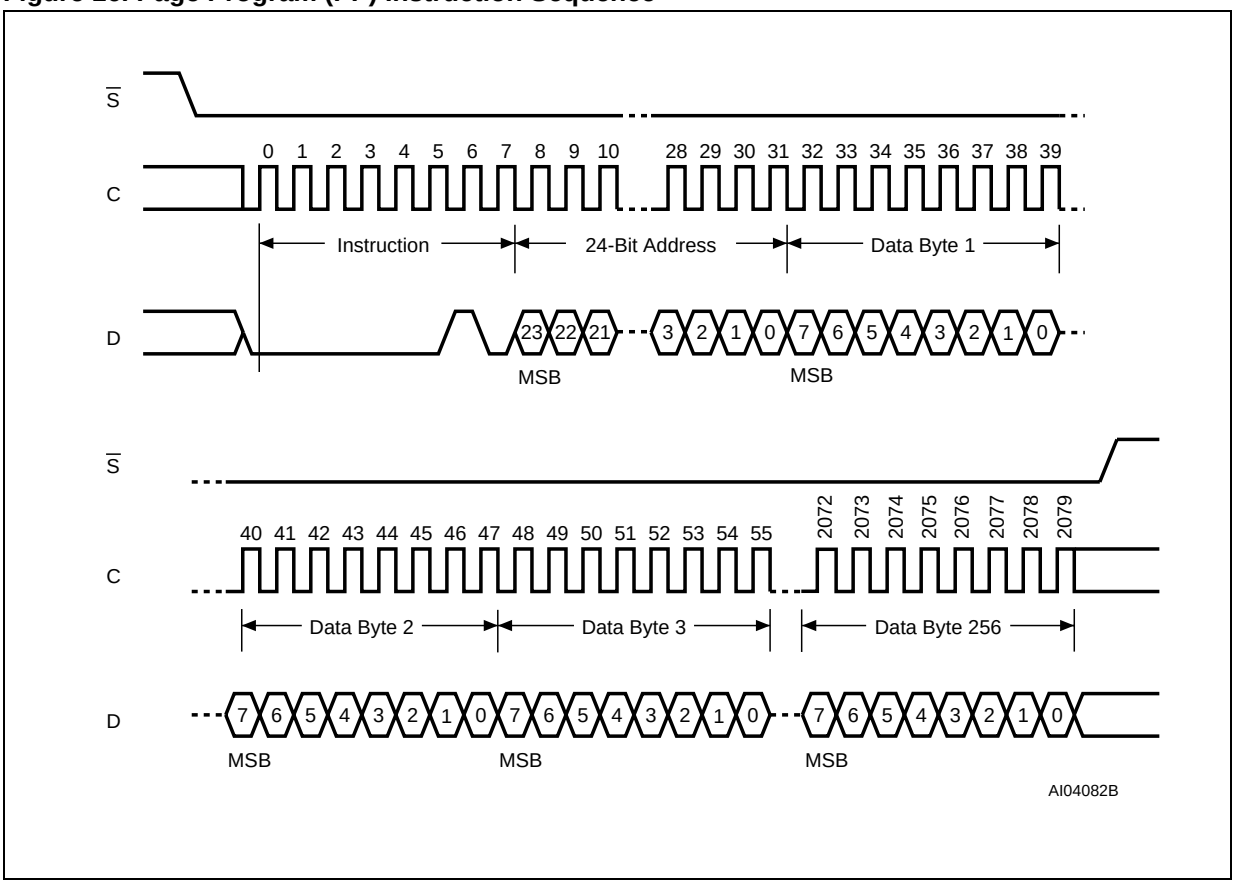
If more than 256 bytes are sent to the device, previously latched data are discarded and the last 256 data bytes are guaranteed to be programmed correctly within the same page. If less than 256 Data bytes are sent to device, they are correctly programmed at the requested addresses without having any effects on the other bytes of the same page.

Chip Select (S) must be driven High after the eighth bit of the last data byte has been latched in, otherwise the Page Program (PP) instruction is not executed.

As soon as Chip Select (S) is driven High, the self-timed Page Program cycle (whose duration is t_{PP}) is initiated. While the Page Program cycle is in progress, the Status Register may be read to check the value of the Write In Progress (WIP) bit. The Write In Progress (WIP) bit is 1 during the self-timed Page Program cycle, and is 0 when it is completed. At some unspecified time before the cycle is completed, the Write Enable Latch (WEL) bit is reset.

A Page Program (PP) instruction applied to a page which is protected by the Block Protect (BP2, BP1, BP0) bits (see Table 2. and Table 3.) is not executed.

Figure 16. Page Program (PP) Instruction Sequence



Sector Erase (SE)

The Sector Erase (SE) instruction sets to 1 (FFh) all bits inside the chosen sector. Before it can be accepted, a Write Enable (WREN) instruction must previously have been executed. After the Write Enable (WREN) instruction has been decoded, the device sets the Write Enable Latch (WEL).

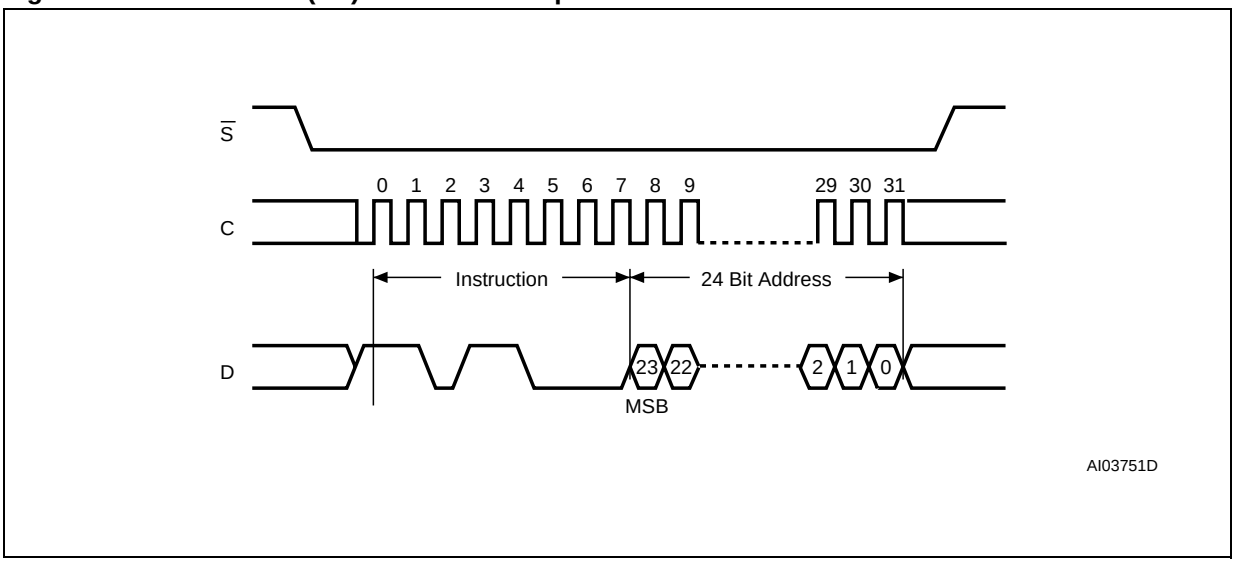
The Sector Erase (SE) instruction is entered by driving Chip Select (S) Low, followed by the instruction code, and three address bytes on Serial Data Input (D). Any address inside the Sector (see Table 3.) is a valid address for the Sector Erase (SE) instruction. Chip Select (S) must be driven Low for the entire duration of the sequence.

The instruction sequence is shown in Figure 17..

Chip Select (S) must be driven High after the eighth bit of the last address byte has been latched in, otherwise the Sector Erase (SE) instruction is not executed. As soon as Chip Select (S) is driven High, the self-timed Sector Erase cycle (whose duration is t_{SE}) is initiated. While the Sector Erase cycle is in progress, the Status Register may be read to check the value of the Write In Progress (WIP) bit. The Write In Progress (WIP) bit is 1 during the self-timed Sector Erase cycle, and is 0 when it is completed. At some unspecified time before the cycle is completed, the Write Enable Latch (WEL) bit is reset.

A Sector Erase (SE) instruction applied to a page which is protected by the Block Protect (BP2, BP1, BP0) bits (see Table 2. and Table 3.) is not executed.

Figure 17. Sector Erase (SE) Instruction Sequence



Note: Address bit A23 is Don't Care.

Bulk Erase (BE)

The Bulk Erase (BE) instruction sets all bits to 1 (FFh). Before it can be accepted, a Write Enable (WREN) instruction must previously have been executed. After the Write Enable (WREN) instruction has been decoded, the device sets the Write Enable Latch (WEL).

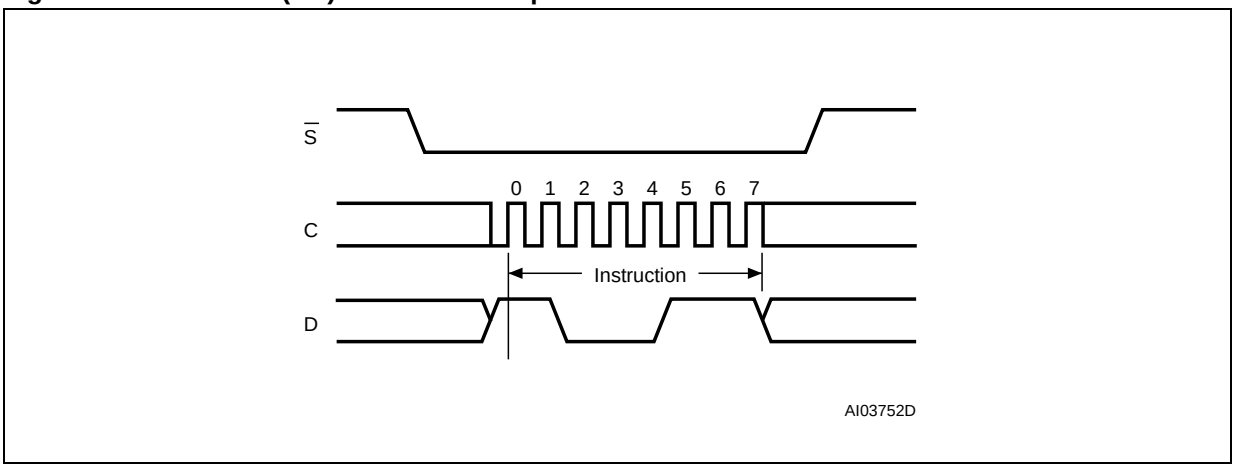
The Bulk Erase (BE) instruction is entered by driving Chip Select (S) Low, followed by the instruction code on Serial Data Input (D). Chip Select (S) must be driven Low for the entire duration of the sequence.

The instruction sequence is shown in Figure 18..

Chip Select (S) must be driven High after the eighth bit of the instruction code has been latched in, otherwise the Bulk Erase instruction is not executed. As soon as Chip Select (S) is driven High, the self-timed Bulk Erase cycle (whose duration is t_{BE}) is initiated. While the Bulk Erase cycle is in progress, the Status Register may be read to check the value of the Write In Progress (WIP) bit. The Write In Progress (WIP) bit is 1 during the self-timed Bulk Erase cycle, and is 0 when it is completed. At some unspecified time before the cycle is completed, the Write Enable Latch (WEL) bit is reset.

The Bulk Erase (BE) instruction is executed only if all Block Protect (BP2, BP1, BP0) bits are 0. The Bulk Erase (BE) instruction is ignored if one, or more, sectors are protected.

Figure 18. Bulk Erase (BE) Instruction Sequence



Read Electronic Signature (RES)

The instruction is used to read, on Serial Data Output (Q), the old-style 8-bit Electronic Signature, whose value for the *M25P64* is *16h*.

Please note that this is not the same as, or even a subset of, the JEDEC 16-bit Electronic Signature that is read by the Read Identifier (RDID) instruction. The old-style Electronic Signature is supported for reasons of backward compatibility, only, and should not be used for new designs. New designs should, instead, make use of the JEDEC 16-bit Electronic Signature, and the Read Identifier (RDID) instruction.

The device is first selected by driving Chip Select ($\overline{S}$) Low. The instruction code is followed by 3 dummy bytes, each bit being latched-in on Serial Data Input (D) during the rising edge of Serial Clock (C). Then, the old-style 8-bit Electronic Signature, stored in the memory, is shifted out on Serial Data Output (Q), each bit being shifted out during the falling edge of Serial Clock (C).

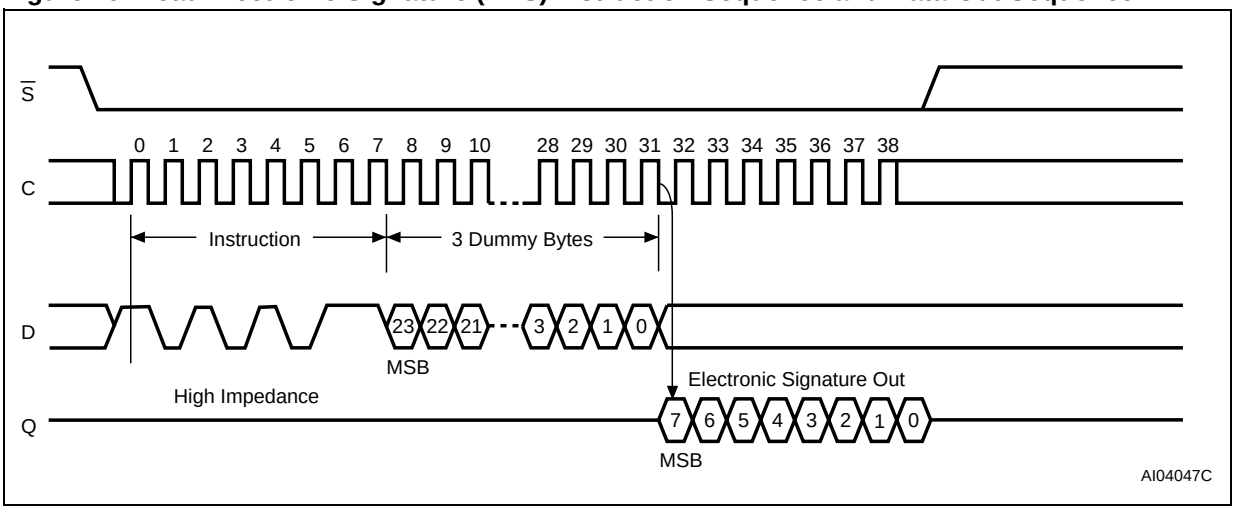
The instruction sequence is shown in Figure 19.

The Read Electronic Signature (RES) instruction is terminated by driving Chip Select ($\overline{S}$) High after the Electronic Signature has been read at least once. Sending additional clock cycles on Serial Clock (C), while Chip Select ($\overline{S}$) is driven Low, cause the Electronic Signature to be output repeatedly.

When Chip Select ($\overline{S}$) is driven High, the device is put in the Standby Power mode. Once in the Standby Power mode, the device waits to be selected, so that it can receive, decode and execute instructions.

Driving Chip Select ($\overline{S}$) High after the 8-bit instruction byte has been received by the device, but before the whole of the 8-bit Electronic Signature has been transmitted for the first time, still ensures that the device is put into Standby Power mode. Once in the Standby Power mode, the device waits to be selected, so that it can receive, decode and execute instructions.

Figure 19. Read Electronic Signature (RES) Instruction Sequence and Data-Out Sequence



Note: The value of the 8-bit Electronic Signature, for the M25P64, is 16h.

POWER-UP AND POWER-DOWN

At Power-up and Power-down, the device must not be selected (that is Chip Select (S) must follow the voltage applied on V_{CC}) until V_{CC} reaches the correct value:

– V_{CC}(min) at Power-up, and then for a further delay of t_{VSL}

– V_{SS} at Power-down

Usually a simple pull-up resistor on Chip Select ($\overline{S}$) can be used to ensure safe and proper Power-up and Power-down.

To avoid data corruption and inadvertent write operations during Power-up, a Power On Reset (POR) circuit is included. The logic inside the device is held reset while V_{CC} is less than the Power On Reset (POR) threshold voltage, V_{WI} – all operations are disabled, and the device does not respond to any instruction.

Moreover, the device ignores all Write Enable (WREN), Page Program (PP), Sector Erase (SE), Bulk Erase (BE) and Write Status Register (WRSR) instructions until a time delay of t_{PUW} has elapsed after the moment that V_{CC} rises above the V_{WI} threshold. However, the correct operation of the device is not guaranteed if, by this time, V_{CC} is still below V_{CC}(min). No Write Status Register, Program or Erase instructions should be sent until the later of:

– t_{PUW} after V_{CC} passed the V_{WI} threshold

– t_{VSL} after V_{CC} passed the V_{CC}(min) level

These values are specified in Table 8..

If the delay, t_{VSL}, has elapsed, after V_{CC} has risen above V_{CC}(min), the device can be selected for READ instructions even if the t_{PUW} delay is not yet fully elapsed.

At Power-up, the device is in the following state:

– The device is in the Standby Power mode

– The Write Enable Latch (WEL) bit is reset.

Normal precautions must be taken for supply rail decoupling, to stabilize the V_{CC} supply. Each device in a system should have the V_{CC} rail decoupled by a suitable capacitor close to the package pins. (Generally, this capacitor is of the order of 0.1µF).

At Power-down, when V_{CC} drops from the operating voltage, to below the Power On Reset (POR) threshold voltage, V_{WI}, all operations are disabled and the device does not respond to any instruction. (The designer needs to be aware that if a Power-down occurs while a Write, Program or Erase cycle is in progress, some data corruption can result.)

Figure 20. Power-up Timing

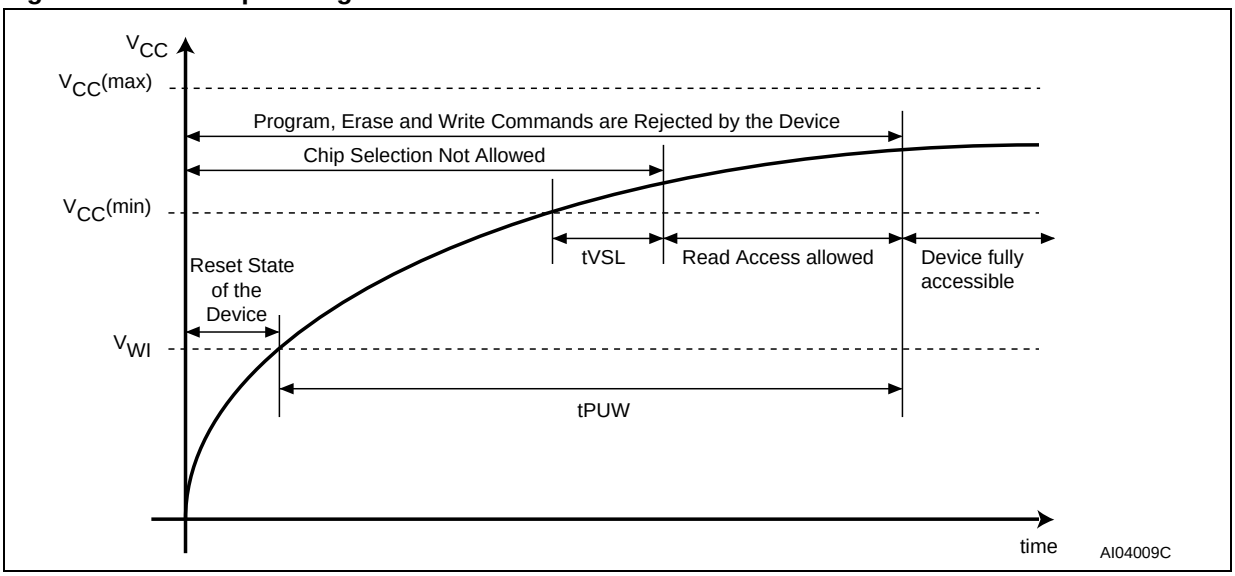


Table 8. Power-Up Timing and V_{WI} Threshold

Symbol	Parameter	Min.	Max.	Unit
t_{VSL}(1)	V_{CC}(min) to $\overline{S}$ low	30		µs
t_{PUW}(1)	Time delay to Write instruction	1	10	ms
V_{WI}(1)	Write Inhibit Voltage	1.5	2.5	V

Note: 1. These parameters are characterized only.

INITIAL DELIVERY STATE

The device is delivered with the memory array erased: all bits are set to 1 (each byte contains FFh). The Status Register contains 00h (all Status Register bits are 0).

MAXIMUM RATING

Stressing the device outside the ratings listed in Table 9. may cause permanent damage to the device. These are stress ratings only, and operation of the device at these, or any other conditions outside those indicated in the Operating sections of this specification, is not implied. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability. Refer also to the STMicroelectronics SURE Program and other relevant quality documents.

Table 9. Absolute Maximum Ratings

Symbol	Parameter	Min.	Max.	Unit
T_{STG}	Storage Temperature	–65	150	°C
T_{LEAD}	Lead Temperature during Soldering	See note (1)		°C
V_{IO}	Input and Output Voltage (with respect to Ground)	–0.5	4.0	V
V_{CC}	Supply Voltage	–0.2	4.0	V
V_{ESD}	Electrostatic Discharge Voltage (Human Body model) 2	–2000	2000	V

Note: 1. Compliant with JEDEC Std J-STD-020C (for small body, Sn-Pb or Pb assembly), the ST ECOPACK® 7191395 specification, and the European directive on Restrictions on Hazardous Substances (RoHS) 2002/95/EU
2. JEDEC Std JESD22-A114A (C1=100 pF, R1=1500 Ω, R2=500 Ω)

DC AND AC PARAMETERS

This section summarizes the operating and measurement conditions, and the DC and AC characteristics of the device. The parameters in the DC and AC Characteristic tables that follow are derived from tests performed under the Measurement Conditions summarized in the relevant tables. Designers should check that the operating conditions in their circuit match the measurement conditions when relying on the quoted parameters.

Table 10. Operating Conditions

Symbol	Parameter	Min.	Max.	Unit
V_{CC}	Supply Voltage	2.7	3.6	V
T_A	Ambient Operating Temperature	–40	85	°C

Table 11. AC Measurement Conditions

Symbol	Parameter	Min.	Max.	Unit
C_L	Load Capacitance	30		pF
	Input Rise and Fall Times		5	ns
	Input Pulse Voltages	$0.2V_{CC}$ to $0.8V_{CC}$		V
	Input Timing Reference Voltages	$0.3V_{CC}$ to $0.7V_{CC}$		V
	Output Timing Reference Voltages	V_{CC} / 2		V

Note: Output Hi-Z is defined as the point where data out is no longer driven.

Figure 21. AC Measurement I/O Waveform

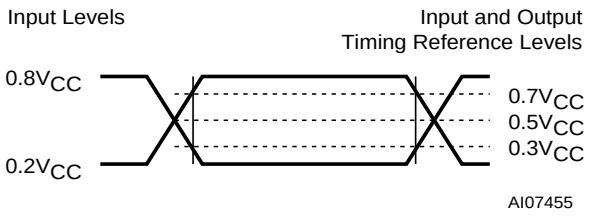


Table 12. Capacitance

Symbol	Parameter	Test Condition	Min.	Max.	Unit
C_{OUT}	Output Capacitance (Q)	V_{OUT} = 0V		8	pF
C_{IN}	Input Capacitance (other pins)	V_{IN} = 0V		6	pF

Note: Sampled only, not 100% tested, at T_A=25°C and a frequency of 20 MHz.

Table 13. DC Characteristics

Symbol	Parameter	Test Condition (in addition to those in Table 10.)	Min.	Max.	Unit
I_{LI}	Input Leakage Current			± 2	µA
I_{LO}	Output Leakage Current			± 2	µA
I_{CC1}	Standby Current	$\overline{S}$ = V_{CC}, V_{IN} = V_{SS} or V_{CC}		50	µA
I_{CC3}	Operating Current (READ)	C = 0.1V_{CC} / 0.9.V_{CC} at 50MHz, Q = open		8	mA
		C = 0.1V_{CC} / 0.9.V_{CC} at 20MHz, Q = open		4	mA
I_{CC4}	Operating Current (PP)	$\overline{S}$ = V_{CC}		15	mA
I_{CC5}	Operating Current (WRSR)	$\overline{S}$ = V_{CC}		20	mA
I_{CC6}	Operating Current (SE)	$\overline{S}$ = V_{CC}		20	mA
I_{CC7}	Operating Current (BE)	$\overline{S}$ = V_{CC}		20	mA
V_{IL}	Input Low Voltage		– 0.5	0.3V_{CC}	V
V_{IH}	Input High Voltage		0.7V_{CC}	V_{CC}+0.2	V
V_{OL}	Output Low Voltage	I_{OL} = 1.6mA		0.4	V
V_{OH}	Output High Voltage	I_{OH} = –100µA	V_{CC}–0.2		V

Table 14. AC Characteristics

Test conditions specified in Table 10. and Table 11.						
Symbol	**Alt.**	**Parameter**	**Min.**	**Typ.**	**Max.**	**Unit**
f_C	f_C	Clock Frequency for the following instructions: FAST_READ, PP, SE, BE, RES, WREN, WRDI, RDID, RDSR, WRSR	D.C.		50	MHz
f_R		Clock Frequency for READ instructions	D.C.		20	MHz
t_{CH} (1)	t_{CLH}	Clock High Time	9			ns
t_{CL} (1)	t_{CLL}	Clock Low Time	9			ns
t_{CLCH} (2)		Clock Rise Time[3] (peak to peak)	0.1			V/ns
t_{CHCL} (2)		Clock Fall Time[3] (peak to peak)	0.1			V/ns
t_{SLCH}	t_{CSS}	$\overline{S}$ Active Setup Time (relative to C)	5			ns
t_{CHSL}		$\overline{S}$ Not Active Hold Time (relative to C)	5			ns
t_{DVCH}	t_{DSU}	Data In Setup Time	2			ns
t_{CHDX}	t_{DH}	Data In Hold Time	5			ns
t_{CHSH}		$\overline{S}$ Active Hold Time (relative to C)	5			ns
t_{SHCH}		$\overline{S}$ Not Active Setup Time (relative to C)	5			ns
t_{SHSL}	t_{CSH}	$\overline{S}$ Deselect Time	100			ns
t_{SHQZ} (2)	t_{DIS}	Output Disable Time			8	ns
t_{CLQV}	t_V	Clock Low to Output Valid			8	ns
t_{CLQX}	t_{HO}	Output Hold Time	0			ns
t_{HLCH}		$\overline{HOLD}$ Setup Time (relative to C)	5			ns
t_{CHHH}		$\overline{HOLD}$ Hold Time (relative to C)	5			ns
t_{HHCH}		HOLD Setup Time (relative to C)	5			ns
t_{CHHL}		HOLD Hold Time (relative to C)	5			ns
t_{HHQX} (2)	t_{LZ}	HOLD to Output Low-Z			8	ns
t_{HLQZ} (2)	t_{HZ}	$\overline{HOLD}$ to Output High-Z			8	ns
t_{WHSL} (4)		Write Protect Setup Time	20			ns
t_{SHWL} (4)		Write Protect Hold Time	100			ns
t_W		Write Status Register Cycle Time		5	15	ms
t_{PP}		Page Program Cycle Time		1.4	5	ms
t_{SE}		Sector Erase Cycle Time		1	3	s
t_{BE}		Bulk Erase Cycle Time		68	160	s

Note: 1. $t_{CH} + t_{CL}$ must be greater than or equal to $1/ f_C$(max)
2. Value guaranteed by characterization, not 100% tested in production.
3. Expressed as a slew-rate.
4. Only applicable as a constraint for a WRSR instruction when SRWD is set at 1.

Figure 22. Serial Input Timing

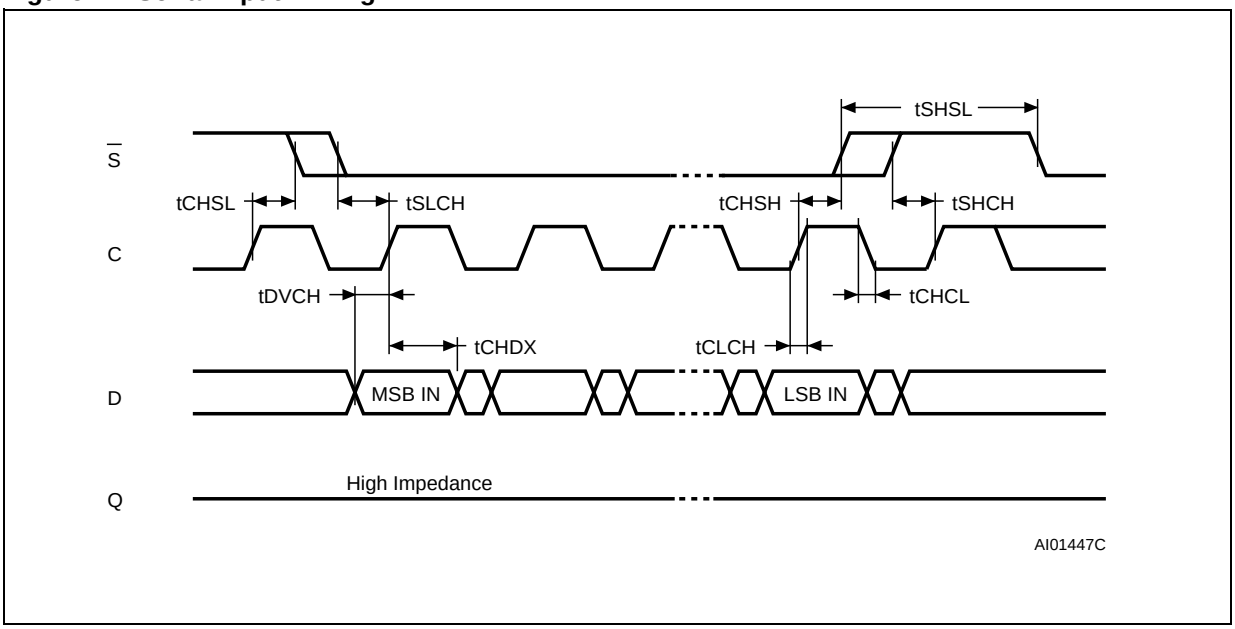


Figure 23. Write Protect Setup and Hold Timing during WRSR when SRWD=1

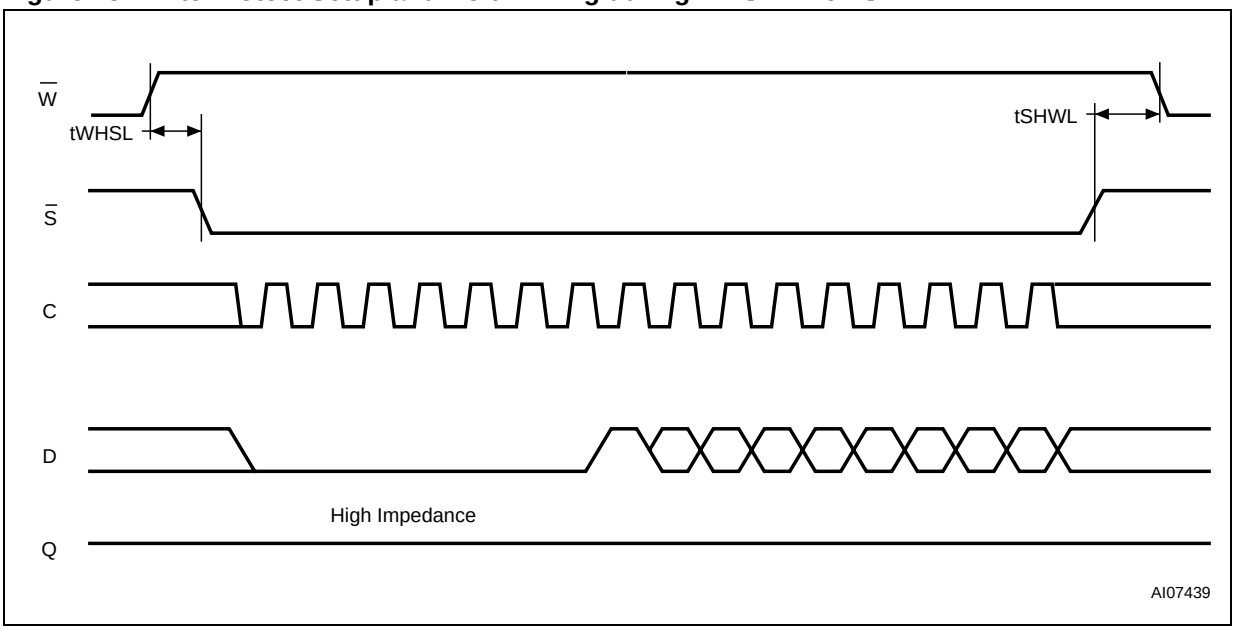


Figure 24. Hold Timing

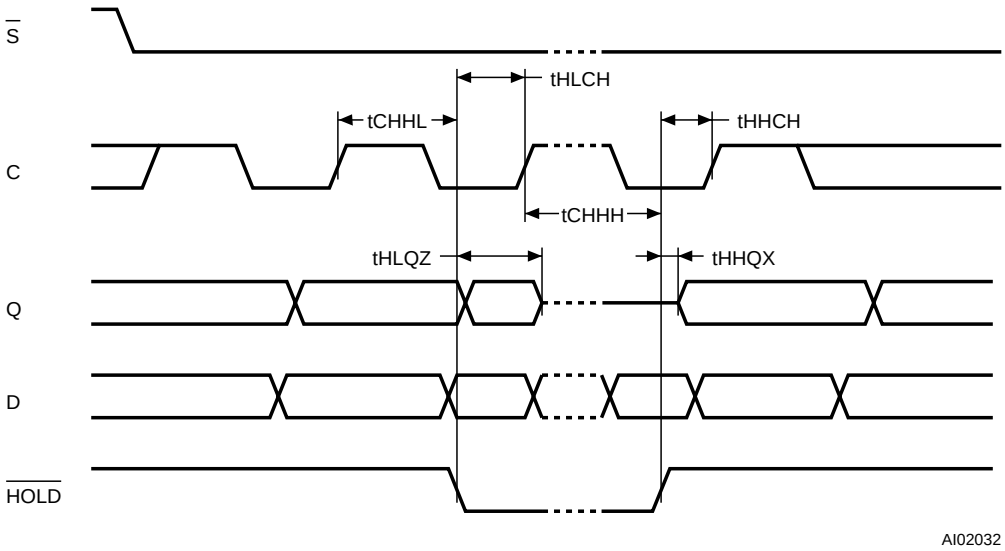
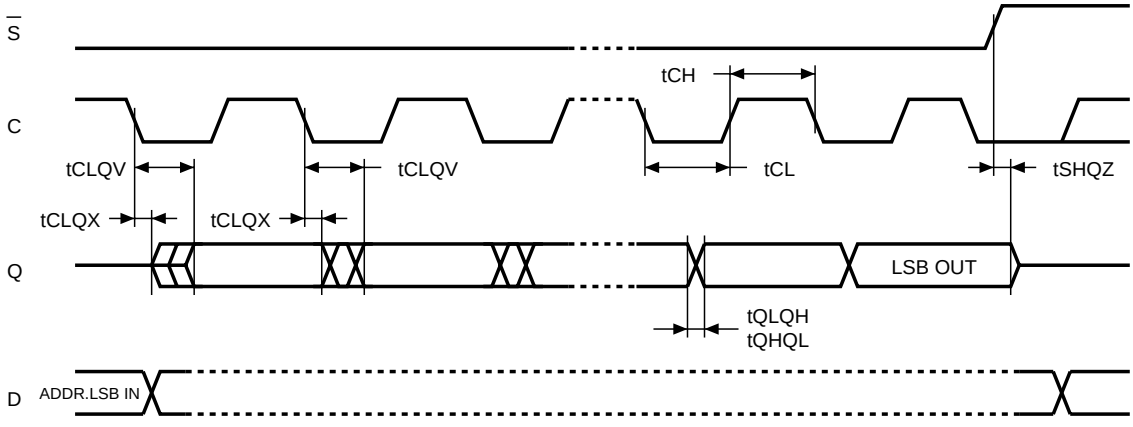
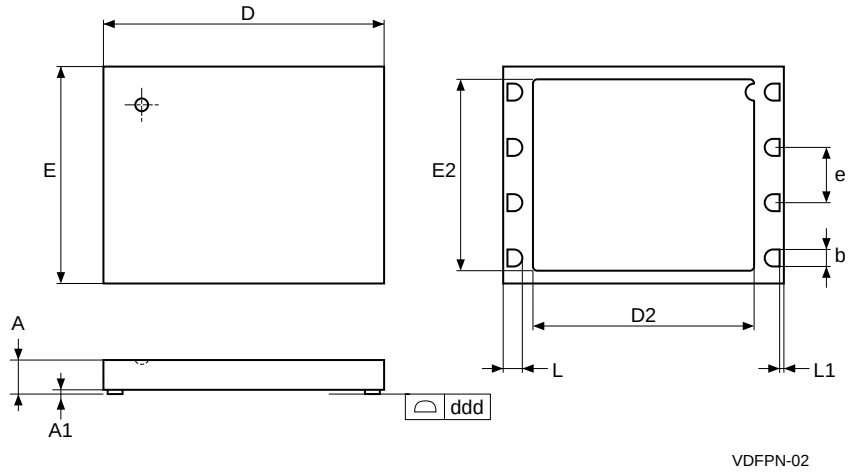


Figure 25. Output Timing



PACKAGE MECHANICAL

Figure 26. MLP8, 8-lead Very thin Dual Flat Package No lead, 8x6mm, Package Outline

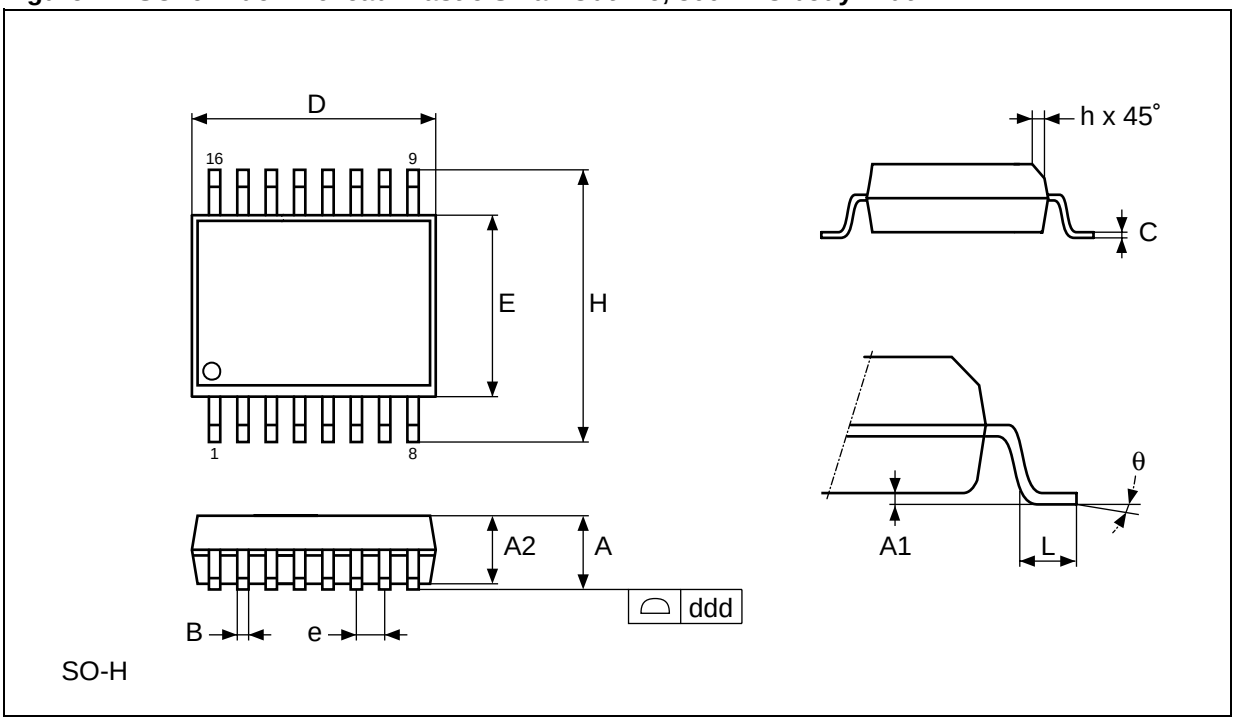


Note: Drawing is not to scale.

Table 15. MLP8, 8-lead Very thin Dual Flat Package No lead, 8x6mm, Package Mechanical Data

Symbol	millimeters			inches		
	Typ.	Min.	Max.	Typ.	Min.	Max.
A	0.85		1.00	0.0335		0.0394
A1		0.00	0.05		0.0000	0.0020
b	0.40	0.35	0.48	0.0157	0.0138	0.0189
D	8.00			0.3150		
D2	6.40			0.2520		
ddd			0.05			0.0020
E	6.00			0.2362		
E2	4.80			0.1890		
e	1.27	–	–	0.0500	–	–
K		0.20			0.0079	
L	0.50	0.45	0.60	0.0197	0.0177	0.0236
L1			0.15			0.0059
N	8			8		

Figure 27. SO16 wide – 16 lead Plastic Small Outline, 300 mils body width



Note: Drawing is not to scale.

Table 16. SO16 wide – 16 lead Plastic Small Outline, 300 mils body width

Symbol	millimeters			inches		
	Typ	Min	Max	Typ	Min	Max
A		2.35	2.65		0.093	0.104
A1		0.10	0.30		0.004	0.012
B		0.33	0.51		0.013	0.020
C		0.23	0.32		0.009	0.013
D		10.10	10.50		0.398	0.413
E		7.40	7.60		0.291	0.299
e	1.27	–	–	0.050	–	–
H		10.00	10.65		0.394	0.419
h		0.25	0.75		0.010	0.030
L		0.40	1.27		0.016	0.050
θ		0°	8°		0°	8°
ddd			0.10			0.004

PART NUMBERING

Table 17. Ordering Information Scheme

Example: M25P64 – V MF 6 T P

Device Type
M25P = Serial Flash Memory for Code Storage

Device Function
64 = 64Mbit (8M x 8)

Operating Voltage
V = V_{CC} = 2.7 to 3.6V

Package
MF = SO16 (300 mil width)
ME = VDFPN8 8x6mm (MLP8)

Device Grade
6 = Industrial temperature range, –40 to 85 °C.
Device tested with standard test flow

Option
blank = Standard Packing
T = Tape and Reel Packing

Plating Technology
blank = Standard SnPb plating
P or G = RoHS compliant

For a list of available options (speed, package, etc.) or for further information on any aspect of this device, please contact your nearest ST Sales Office.

REVISION HISTORY

Table 18. Document Revision History

Date	Rev.	Description of Revision
28-Apr-2003	0.1	Target Specification Document written in brief form
15-May-2003	0.2	Target Specification Document written in full
20-Jun-2003	0.3	8x6 MLP8 and SO16(300 mil) packages added
18-Jul-2003	0.4	t_{PP}, t_{SE} and t_{BE} revised
02-Sep-2003	0.5	Voltage supply range changed
19-Sep-2003	0.6	Table of contents, warning about exposed paddle on MLP8, and Pb-free options added
17-Dec-2003	0.7	Value of t_{VSL}(min) V_{WI}, t_{PP}(typ) and t_{BE}(typ) changed. MLP8 package removed.
15-Nov-2004	1.0	Document status promoted from Target Specification to Preliminary Data. 8x6 MLP8 package added. Minor wording changes.
24-Feb-2005	2.0	Deep Power-Down mode removed from datasheet (Figure 19., Read Electronic Signature (RES) Instruction Sequence and Data-Out Sequence modified and tRES1 and tRES2 removed from Table 14., AC Characteristics). SO16 Wide package specifications updated. End timing line of t_{SHQZ} modified in Figure 25., Output Timing. Figures moved below the corresponding instructions in the INSTRUCTIONS section.

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